

Title (en)

Wafer-level MEMS package and manufacturing method thereof

Title (de)

MEMS-Gehäuse auf Waferebene und dessen Herstellungsverfahren

Title (fr)

Boîtier pour MEMS au niveau de plaquette et sa méthode de fabrication

Publication

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Application

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Priority

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Abstract (en)

The present invention is related in general to a wafer-level packaging technique for micro-electro-mechanical systems (MEMS). A cap structure (4) is provided encapsulating a MEMS element (1) formed on a base substrate (2). A channel (9) communicates etching holes (8,7) provided on said cap structure (4), for the passage of an etching fluid (12) to a chamber (3) in which the MEMS element is housed. The holes (8,7) are arranged in such a manner that they do not overlap, which allows the provision of a large number of etching holes above the MEMS element (1), but prevents a sealing material (10) from reaching the MEMS element. The invention provides a low cost wafer-level packaging technique for MEMS devices, that reduces the total etching time of the sacrificial material and provides a reinforced protective cap structure for the MEMS package.

IPC 8 full level

B81C 99/00 (2010.01)

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Citation (applicant)

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